

Patent [19]

[11] Patent Number: 08059940
[45] Date of Patent: Mar. 05, 1996

[54] ELECTROCONDUCTIVE FLUORORUBBER COMPOSITION FOR CROSSLINKING AND MOLDING THEREFROM

[21] Appl. No.: 06222580 JP06222580 JP

[22] Filed: Aug. 23, 1994

[51] Int. Cl.⁶ C08L02712 ; C08K00304; C08K00514; C08K00517; C08K00550

[57] ABSTRACT

PURPOSE: To obtain the subject composition excellent in electrical conductivity and capable of providing a crosslinked coating film having low viscosity, low hardness, etc., by blending iodine and/or a bromine-containing fluororubber with an onium salt compound, an electroconductive filler, a crosslinking agent and a peroxide compound at a specific ratio.

CONSTITUTION: This composition is obtained by blending (A) 100 pts. wt. of an iodine- and/or bromine-containing fluororubber with (B) preferably 0.1-20 pts. wt. of an onium salt compound of the formula (R⁹us a 1-20C alkyl, allyl, etc.; R¹⁰to R¹² are each an aryl or a substituted aryl; A is an anion such as a halide, a sulfate or a sulfite), (C) 1-20 pts. wt. of an electroconductive filler (preferably 30-400ml/100g as DBP oil absorbing amount) (D) 0.1-10 pts. wt. of a crosslinking agent, (E) 0.1-10 pts. wt. of a peroxide compound. The electroconductive fluororubber molding is obtained by foaming, crosslinking and molding a composition containing (F) a foaming agent in addition to the above components of the composition. The electroconductive fluororubber molding is preferably a coating film having 40-50Hs (Typec) hardness and 10⁶ to 10¹¹ &mega; resistance.

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PATENT ABSTRACTS OF JAPAN

(11)Publication number : 08-059940

(43)Date of publication of application : 05.03.1996

(51)Int.Cl. C08L 27/12
 C08K 3/04
 C08K 5/14
 C08K 5/17
 C08K 5/50

(21)Application number : 06-222580

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(22)Date of filing : 23.08.1994

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(54) ELECTROCONDUCTIVE FLUORORUBBER COMPOSITION FOR CROSSLINKING AND MOLDING THEREFROM

(57)Abstract:

PURPOSE: To obtain the subject composition excellent in electrical conductivity and capable of providing a crosslinked coating film having low viscosity, low hardness, etc., by blending iodine and/or a bromine-containing fluororubber with an onium salt compound, an electroconductive filler, a crosslinking agent and a peroxide compound at a specific ratio.



CONSTITUTION: This composition is obtained by blending (A) 100 pts. wt. of an iodine- and/or bromine-containing fluororubber with (B) preferably 0.1-20 pts.wt. of an onium salt compound of the formula (R9 is a 1-20C alkyl, allyl, etc.; R10 to R12 are each an aryl or a substituted aryl; A is an anion such as a halide, a sulfate or a sulfite), (C) 1-20 pts.wt. of an electroconductive filler (preferably 30-400ml/100g as DBP oil absorbing amount) (D) 0.1-10 pts.wt. of a crosslinking agent, (E) 0.1-10 pts.wt. of a peroxide compound. The electroconductive fluororubber molding is obtained by foaming, crosslinking and molding a composition containing (F) a foaming agent in addition to the above components of the composition. The electroconductive

fluororubber molding is preferably a coating film having 40-50Hs (Typec) hardness and 106 to 1011Ω resistance.

LEGAL STATUS

[Date of request for examination] 30.06.1999

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 3312501

[Date of registration] 31.05.2002

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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(19)日本国特許庁 (JP)

(12) **公開特許公報 (A)**

(11)特許出願公開番号

特開平8-59940

(43)公開日 平成8年(1996)3月5日

(51)Int.Cl. ⁶	識別記号	序内整理番号	F I	技術表示箇所
C 08 L 27/12	K J M			
C 08 K 3/04	K J F			
5/14	K F Y			
5/17	K J K			
5/50				

審査請求 未請求 請求項の数9 F D (全 9 頁)

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(54)【発明の名称】 架橋用導電性フッ素ゴム組成物及び成形品

(57)【要約】

【目的】 優れた導電性を有し、組成物の粘度が低く、且つ低硬度で抵抗値も安定している架橋被膜を与えるフッ素ゴム組成物及びこの組成物を用いて得られる導電性フッ素ゴム成形品を提供する。

【構成】 ヨウ素及び/又は臭素含有フッ素ゴム 10重量部に対して、オニウム塩化合物 0.1~20重量部、導電性フィラー 1~20重量部、架橋剤 0.1~10重量部、ペークサイド化合物 0.1~10重量部を配合したことを特徴とする架橋用導電性フッ素ゴム組成物及びこれより得られる導電性フッ素ゴム成形品。